

FEATURES

0.5 Ω typical on resistance
0.8 Ω maximum on resistance at 125°C
1.65 V to 3.6 V operation
Automotive temperature range: -40°C to +125°C
Guaranteed leakage specifications up to 125°C
High current carrying capability: 300 mA continuous
Rail-to-rail switching operation
Fast switching times <20 ns
Typical power consumption: <0.1 μ W

APPLICATIONS

Cellular phones
 PDAs
 MP3 players
 Power routing
 Battery-powered systems
 PCMCIA cards
 Modems
 Audio and video signal routing
 Communication systems

GENERAL DESCRIPTION

The ADG836L is a low voltage CMOS device containing two independently selectable single-pole, double-throw (SPDT) switches. This device offers ultralow on resistance of less than 0.8 Ω over the full temperature range. The ADG836L is fully specified for 3.3 V, 2.5 V, and 1.8 V supply operation.

Each switch conducts equally well in both directions when on and has an input signal range that extends to the supplies. The ADG836L exhibits break-before-make switching action.

The ADG836L is available in a 10-lead package.

FUNCTIONAL BLOCK DIAGRAM

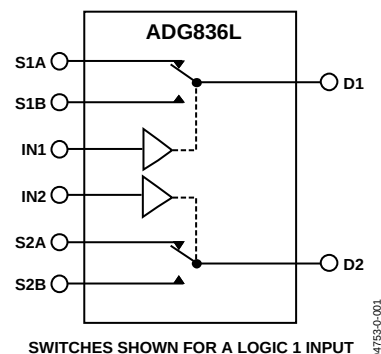


Figure 1.

PRODUCT HIGHLIGHTS

1. Less than 0.8 Ω over full temperature range of -40°C to +125°C.
2. Single 1.65 V to 3.6 V operation.
3. Compatible with 1.8 V CMOS logic.
4. High current handling capability (300 mA continuous current at 3.3 V).
5. Low THD + N (0.02% typ).
6. Small 10-lead MSOP package.

Rev. A

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REVISION HISTORY

5/04—Data Sheet Changed from Rev. 0 to Rev. A

Updated Ordering Guide..... 14

4/04—Revision 0: Initial Version

SPECIFICATIONS

Table 1. $V_{DD} = 2.7\text{ V}$ to 3.6 V , $GND = 0\text{ V}$, unless otherwise noted.¹

Parameter	+25°C	−40°C – +85°C	−40°C – +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V _{DD}	V	V _{DD} = 2.7 V
On Resistance (R _{ON})	0.5			Ω typ	V _{DD} = 2.7 V, V _S = 0 V to V _{DD} , I _S = 10 mA
	0.65	0.75	0.8	Ω max	(Figure 18)
On Resistance Match between Channels (ΔR _{ON})	0.04	0.075	0.08	Ω typ	V _{DD} = 2.7 V, V _S = 0.65 V, I _S = 10 mA
				Ω max	
On Resistance Flatness (R _{FLAT (ON)})	0.1			Ω typ	V _{DD} = 2.7 V, V _S = 0 V to V _{DD} , I _S = 10 mA
		0.15	0.16	Ω max	
LEAKAGE CURRENTS					
Source Off Leakage I _S (OFF)	±0.2			nA typ	V _{DD} = 3.6 V
	±1	±10	±100	nA max	V _S = 0.6 V/3.3 V, V _D = 3.3 V/0.6 V
Channel On Leakage I _D , I _S (ON)	±0.2			nA typ	(Figure 19)
	±1	±15	±120	nA max	V _S = V _D = 0.6 V or 3.3 V (Figure 20)
DIGITAL INPUTS					
Input High Voltage, V _{INH}			2	V min	V _{IN} = V _{INL} or V _{INH}
Input Low Voltage, V _{INL}			0.8	V max	
Input Current, I _{INL} or I _{INH}	0.005			μA typ	
			±0.1	μA max	
C _{IN} , Digital Input Capacitance	4			pF typ	
DYNAMIC CHARACTERISTICS ²					
t _{ON}	21			ns typ	R _L = 50 Ω, C _L = 35 pF
	26	28	29	ns max	V _S = 1.5 V/0 V (Figure 21)
t _{OFF}	4			ns typ	R _L = 50 Ω, C _L = 35 pF
	7	8	9	ns max	V _S = 1.5 V (Figure 21)
Break-before-Make Time Delay (t _{BBM})	17			ns typ	R _L = 50 Ω, C _L = 35 pF
			5	ns min	V _{S1} = V _{S2} = 1.5 V (Figure 22)
Charge Injection	40			pC typ	V _S = 1.5 V, R _S = 0 Ω, C _L = 1 nF (Figure 23)
Off Isolation	−67			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 100 kHz (Figure 24)
Channel-to-Channel Crosstalk	−90			dB typ	S1A–S2A/S1B–S2B (Figure 27)
					R _L = 50 Ω, C _L = 5 pF, f = 100 kHz
	−67			dB typ	S1A–S1B/S2A–S2B (Figure 26)
					R _L = 50 Ω, C _L = 5 pF, f = 100 kHz
Total Harmonic Distortion (THD + N)	0.02			%	R _L = 32 Ω, f = 20 Hz to 20 kHz, V _S = 2 V p-p
Insertion Loss	−0.05			dB typ	R _L = 50 Ω, C _L = 5 pF (Figure 25)
−3 dB Bandwidth	57			MHz typ	R _L = 50 Ω, C _L = 5 pF (Figure 25)
C _S (OFF)	25			pF typ	
C _D , C _S (ON)	75			pF typ	
POWER REQUIREMENTS					
I _{DD}	0.003			μA typ	V _{DD} = 3.6 V
		1	4	μA max	Digital inputs = 0 V or 3.6 V

¹ Temperature range for Y version is −40°C to +125°C.

² Guaranteed by design, not subject to production test.

ADG836L

Table 2. $V_{DD} = 2.5 \text{ V} \pm 0.2 \text{ V}$, $GND = 0 \text{ V}$, unless otherwise noted.¹

Parameter	+25°C	–40°C – +85°C	–40°C – +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V _{DD}	V	
On Resistance (R _{ON})	0.65			Ω typ	V _{DD} = 2.3 V, V _S = 0 V to V _{DD} , I _S = 10 mA (Figure 18)
	0.72	0.8	0.88	Ω max	
On Resistance Match between Channels (ΔR _{ON})	0.04			Ω typ	V _{DD} = 2.3 V, V _S = 0.7 V, I _S = 10 mA
		0.08	0.085	Ω max	
On Resistance Flatness (R _{FLAT (ON)})	0.16			Ω typ	V _{DD} = 2.3 V, V _S = 0 V to V _{DD} , I _S = 10 mA
		0.23	0.24	Ω max	
LEAKAGE CURRENTS					
Source Off Leakage I _S (OFF)	±0.2			nA typ	V _{DD} = 2.7 V V _S = 0.6 V/2.4 V, V _D = 2.4 V/0.6 V
	±0.4	±4	±45	nA max	(Figure 19)
Channel On Leakage I _D , I _S (ON)	±0.2			nA typ	V _S = V _D = 0.6 V or 2.4 V (Figure 20)
	±0.6	±12	±90	nA max	
DIGITAL INPUTS					
Input High Voltage, V _{INH}			1.7	V min	
Input Low Voltage, V _{INL}			0.7	V max	
Input Current I _{INL} or I _{INH}	0.005			μA typ	V _{IN} = V _{INL} or V _{INH}
			±0.1	μA max	
C _{IN} , Digital Input Capacitance	4			pF typ	
DYNAMIC CHARACTERISTICS ²					
t _{ON}	23			ns typ	R _L = 50 Ω, C _L = 35 pF
	29	30	31	ns max	V _S = 1.5 V/0 V (Figure 21)
t _{OFF}	5			ns typ	R _L = 50 Ω, C _L = 35 pF
	7	8	9	ns max	V _S = 1.5 V (Figure 21)
Break-before-Make Time Delay (t _{BBM})	17			ns typ	R _L = 50 Ω, C _L = 35 pF
			5	ns min	V _{S1} = V _{S2} = 1.5 V (Figure 22)
Charge Injection	30			pC typ	V _S = 1.25 V, R _S = 0 Ω, C _L = 1 nF (Figure 23)
Off Isolation	–67			dB typ	R _L = 50 Ω, C _L = 5 pF, f = 100 kHz (Figure 24)
Channel-to-Channel Crosstalk	–90			dB typ	S1A–S2A/S1B–S2B; R _L = 50 V, C _L = 5 pF, f = 100 kHz;Figure 27
	–67			dB typ	S1A–S1B/S2A–S2B; R _L = 50 Ω, C _L = 5 pF, f = 100 kHz Figure 25
Total Harmonic Distortion (THD + N)	0.022			%	R _L = 32 Ω, f = 20 Hz to 20 kHz, V _S = 1.5 V p-p
Insertion Loss	–0.06			dB typ	R _L = 50 Ω, C _L = 5 pF (Figure 25)
–3 dB Bandwidth	57			MHz typ	R _L = 50 Ω, C _L = 5 pF (Figure 25)
C _S (OFF)	25			pF typ	
C _D , C _S (ON)	75			pF typ	
POWER REQUIREMENTS					
I _{DD}	0.003			μA typ	V _{DD} = 2.7 V Digital inputs = 0 V or 2.7 V
		1	4	μA max	

¹ Temperature range for Y version is –40°C to +125°C.

² Guaranteed by design, not subject to production test.

Table 3. $V_{DD} = 1.65\text{ V} \pm 1.95\text{ V}$, $GND = 0\text{ V}$, unless otherwise noted.¹

Parameter	+25°C	–40°C – +85°C	–40°C – +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V_{DD}	V	
On Resistance (R_{ON})	1			Ω typ	$V_{DD} = 1.8\text{ V}$, $V_S = 0\text{ V}$ to V_{DD} , $I_S = 10\text{ mA}$ (Figure 18)
	1.4	2.2	2.2	Ω max	
	2	4	4	Ω typ	$V_{DD} = 1.65\text{ V}$, $V_S = 0\text{ V}$ to V_{DD} , $I_S = 10\text{ mA}$
On Resistance Match between Channels (ΔR_{ON})	0.1			Ω typ	$V_{DD} = 1.65\text{ V}$, $V_S = 0.7\text{ V}$, $I_S = 10\text{ mA}$
LEAKAGE CURRENTS					$V_{DD} = 1.95\text{ V}$
Source Off Leakage I_S (OFF)	± 0.2			nA typ	$V_S = 0.6\text{ V}/1.65\text{ V}$, $V_D = 1.65\text{ V}/0.6\text{ V}$ (Figure 19)
	± 0.4	± 4	± 25	nA max	
Channel On Leakage I_D , I_S (ON)	± 0.2			nA typ	$V_S = V_D = 0.6\text{ V}$ or 1.65 V Figure 20
	± 0.6	± 10	± 75	nA max	
DIGITAL INPUTS					
Input High Voltage, V_{INH}			$0.65 V_{DD}$	V min	
Input Low Voltage, V_{INL}			$0.35 V_{DD}$	V max	
Input Current I_{INL} or I_{INH}	0.005			μA typ	$V_{IN} = V_{INL}$ or V_{INH}
			± 0.1	μA max	
C_{IN} , Digital Input Capacitance	4			pF typ	
DYNAMIC CHARACTERISTICS²					
t_{ON}	28			ns typ	$R_L = 50\ \Omega$, $C_L = 35\text{ pF}$
	37	38	39	ns max	$V_S = 1.5\ \Omega/0\text{ V}$ (Figure 21)
t_{OFF}	7			ns typ	$R_L = 50\ \Omega$, $C_L = 35\text{ pF}$
	9	10	11	ns max	$V_S = 1.5\text{ V}$ (Figure 21)
Break-before-Make Time Delay (t_{BBM})	21			ns typ	$R_L = 50\ \Omega$, $C_L = 35\text{ pF}$
			5	ns min	$V_{S1} = V_{S2} = 1\text{ V}$ (Figure 22)
Charge Injection	20			pC typ	$V_S = 1\text{ V}$, $R_S = 0\text{ V}$, $C_L = 1\text{ nF}$ (Figure 23)
Off Isolation	–67			dB typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 100\text{ kHz}$, (Figure 24)
Channel-to-Channel Crosstalk	–90			dB typ	S1A–S2A/S1B–S2B; $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 100\text{ kHz}$ (Figure 27)
	–67			dB typ	S1A–S1B/S2A–S2B; $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 100\text{ kHz}$ (Figure 25)
Total Harmonic Distortion (THD + N)	0.14			%	$R_L = 32\ \Omega$, $f = 20\text{ Hz}$ to 20 kHz , $V_S = 1.2\text{ V p-p}$
Insertion Loss	–0.08			dB typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$ (Figure 25)
–3 dB Bandwidth	57			MHz typ	$R_L = 50\ \Omega$, $C_L = 5\text{ pF}$ (Figure 25)
C_S (OFF)	25			pF typ	
C_D , C_S (ON)	75			pF typ	
POWER REQUIREMENTS					$V_{DD} = 1.95\text{ V}$
I_{DD}	0.003			μA typ	Digital inputs = 0 V or 1.95 V
		1.0	4	μA max	

¹ Temperature range for Y version is –40°C to +125°C.² Guaranteed by design, not subject to production test.

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 4.

Parameter	Rating
V_{DD} to GND	–0.3 V to +4.6 V
Analog Inputs ¹	–0.3 V to $V_{DD} + 0.3$ V
Digital Inputs ¹	–0.3 V to 4.6 V or 10 mA, whichever occurs first
Peak Current, S or D	
3.3 V Operation	500 mA
2.5 V Operation	460 mA
1.8 V Operation	420 mA (pulsed at 1 ms, 10% Duty Cycle Max)
Continuous Current, S or D	
3.3 V Operation	300 mA
2.5 V Operation	275 mA
1.8 V Operation	250 mA
Operating Temperature Range	
Automotive (Y Version)	–40°C to +125°C
Storage Temperature Range	–65°C to +150°C
Junction Temperature	150°C
MSOP Package	
θ_{JA} Thermal Impedance	206°C/W
θ_{JC} Thermal Impedance	44°C/W
IR Reflow, Peak Temperature	235°C
<20 sec	

¹ Overvoltages at IN, S, or D are clamped by internal diodes. Current should be limited to the maximum ratings given.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

TRUTH TABLE

Table 5.

Logic	Switch A	Switch B
0	Off	On
1	On	Off

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



PIN TERMINOLOGY

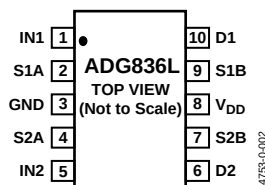


Figure 2. 10-Lead MSOP (RM-10)

Table 6.

Mnemonic	Description
V_{DD}	Most positive power supply potential.
I_{DD}	Positive supply current.
GND	Ground (0 V) reference.
S	Source terminal. May be an input or output.
D	Drain terminal. May be an input or output.
IN	Logic control input.
V_D (V_S)	Analog voltage on terminals D and S.
R_{ON}	Ohmic resistance between terminals D and S.
$R_{FLAT (ON)}$	Flatness is defined as the difference between the maximum and minimum value of on resistance as measured
ΔR_{ON}	On resistance match between any two channels.
I_S (OFF)	Source leakage current with the switch off.
I_D (OFF)	Drain leakage current with the switch off.
I_D, I_S (ON)	Channel leakage current with the switch on.
V_{INL}	Maximum input voltage for Logic 0.
V_{INH}	Minimum input voltage for Logic 1.
I_{INL} (I_{INH})	Input current of the digital input.
C_S (OFF)	Off switch source capacitance. Measured with reference to ground.
C_D (OFF)	Off switch drain capacitance. Measured with reference to ground.
C_D, C_S (ON)	On switch capacitance. Measured with reference to ground.
C_{IN}	Digital input capacitance.
t_{ON}	Delay time between the 50% and the 90% points of the digital input and switch on condition.
t_{OFF}	Delay time between the 50% and the 90% points of the digital input and switch off condition.
t_{BBM}	On or off time measured between the 80% points of both switches when switching from one to another.
Charge Injection	A measure of the glitch impulse transferred from the digital input to the analog output during on-off switching.
Off Isolation	A measure of unwanted signal coupling through an off switch.
Crosstalk	A measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.
–3 dB Bandwidth	The frequency at which the output is attenuated by 3 dB.
On Response	The frequency response of the on switch.
Insertion Loss	The loss due to the on resistance of the switch.
THD + N	The ratio of the harmonic amplitudes plus noise of a signal, to the fundamental.

TYPICAL PERFORMANCE CHARACTERISTICS

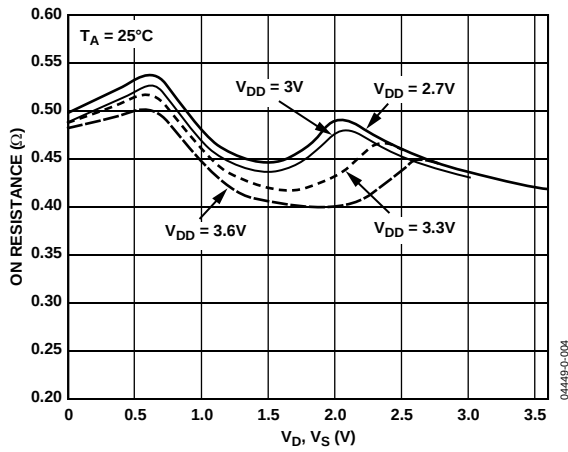


Figure 3. On Resistance vs. V_D (V_S), $V_{DD} = 2.7$ V to 3.6 V

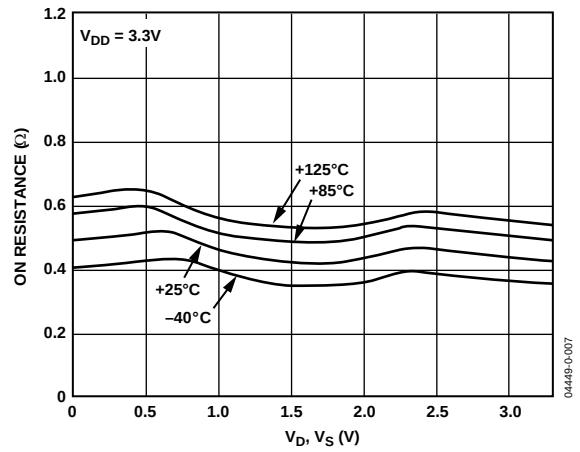


Figure 6. On Resistance vs. V_D (V_S) for Different Temperature, $V_{DD} = 3.3$ V

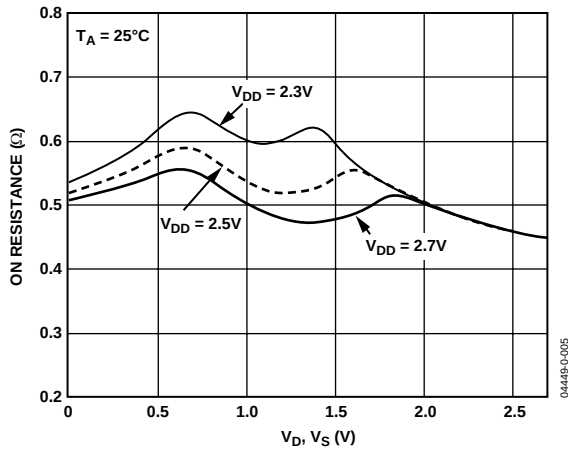


Figure 4. On Resistance vs. V_D (V_S), $V_{DD} = 2.5$ V $\pm$ 0.2 V

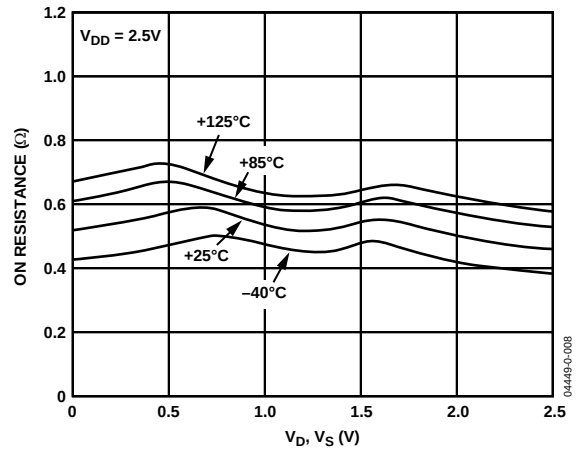


Figure 7. On Resistance vs. V_D (V_S) for Different Temperature, $V_{DD} = 2.5$ V

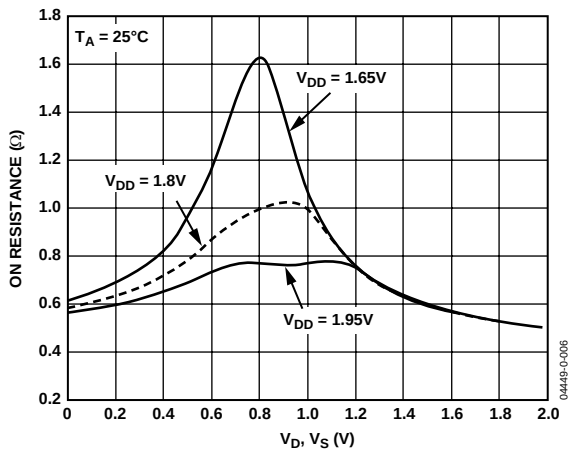


Figure 5. On Resistance vs. V_D (V_S), $V_{DD} = 1.8$ V $\pm$ 0.15 V

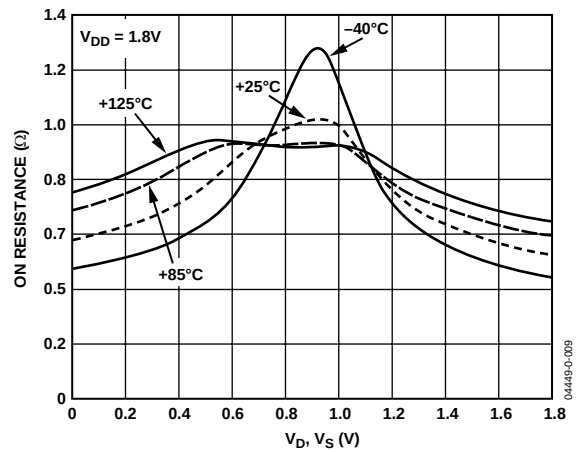


Figure 8. On Resistance vs. V_D (V_S) for Different Temperature, $V_{DD} = 1.8$ V

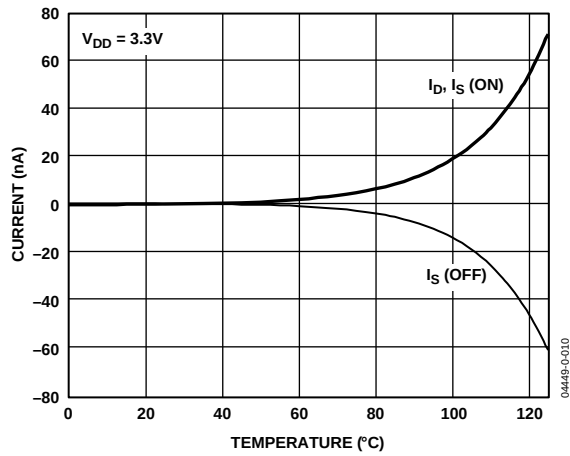


Figure 9. Leakage Current vs. Temperature, $V_{DD} = 3.3V$

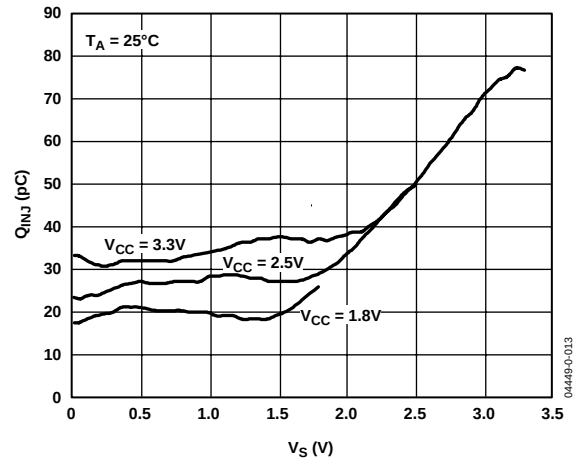


Figure 12. Charge Injection vs. Source Voltage

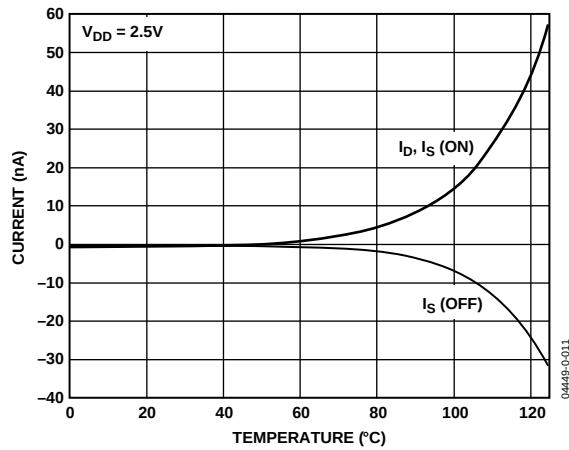


Figure 10. Leakage Current vs. Temperature, $V_{DD} = 2.5V$

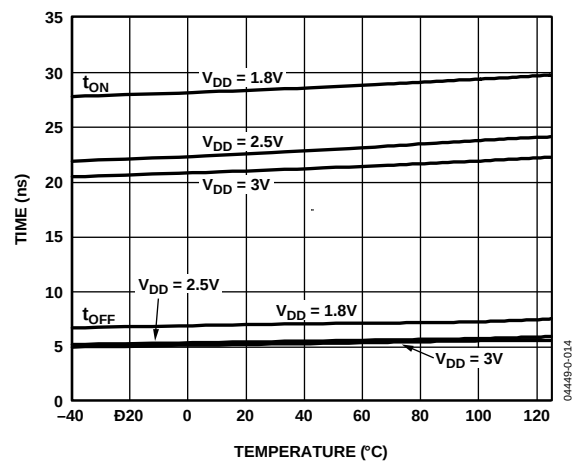


Figure 13. t_{ON}/t_{OFF} Times vs. Temperature

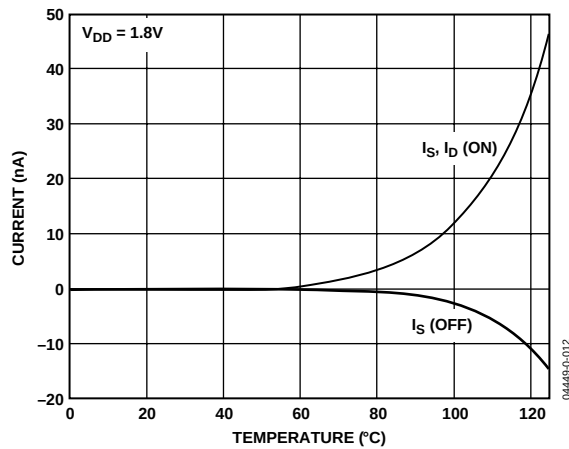


Figure 11. Leakage Current vs. Temperature, $V_{DD} = 1.8V$

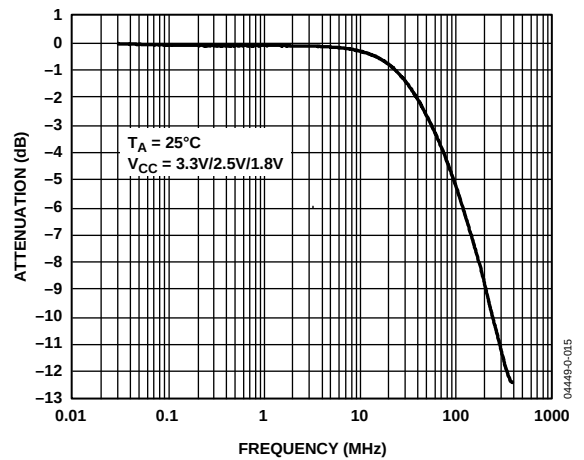


Figure 14. Bandwidth

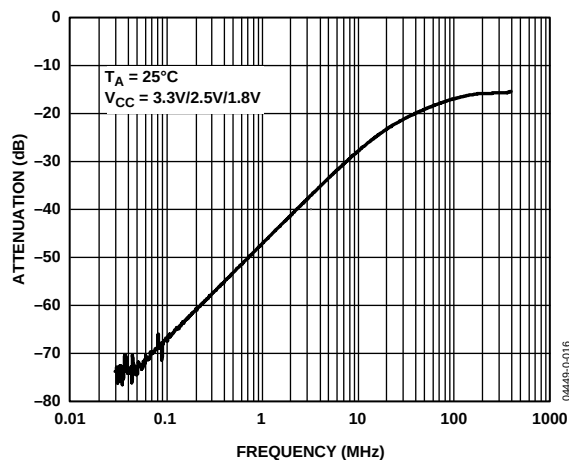


Figure 15. Off Isolation vs. Frequency

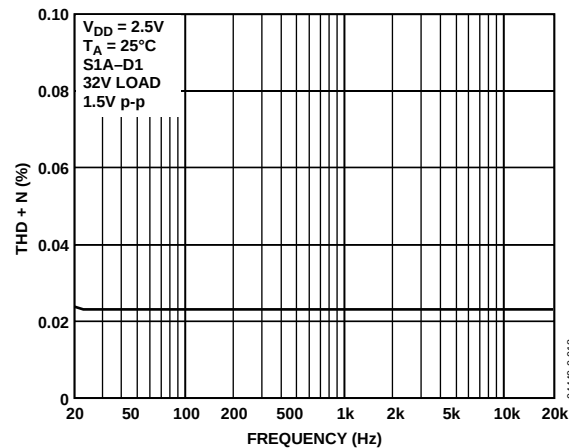


Figure 17. Total Harmonic Distortion + Noise

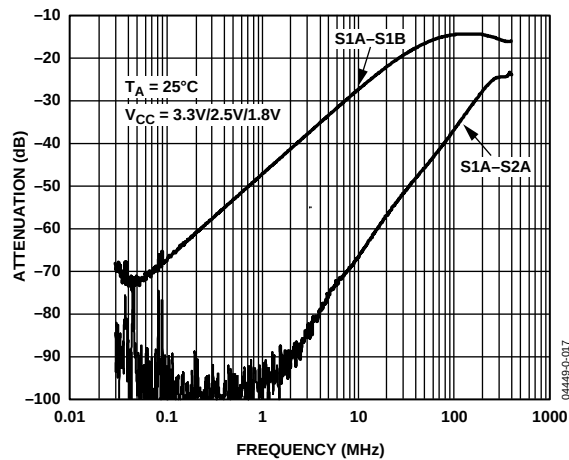


Figure 16. Crosstalk vs. Frequency

TEST CIRCUITS

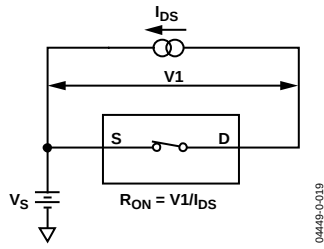


Figure 18. On Resistance

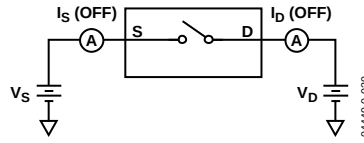


Figure 19. Off Leakage

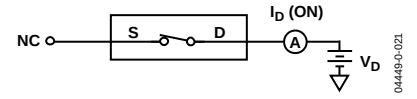


Figure 20. On Leakage

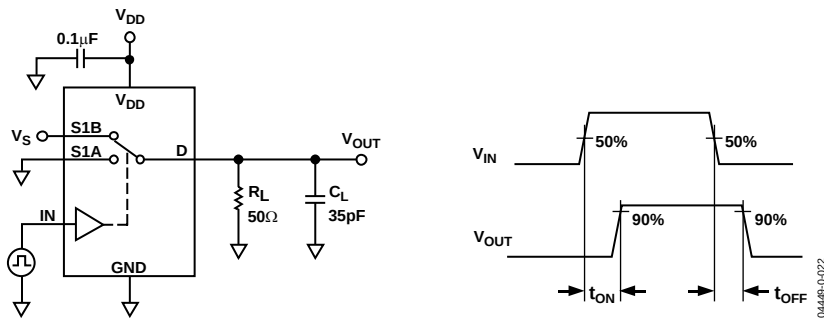


Figure 21. Switching Times, t_{ON} , t_{OFF}

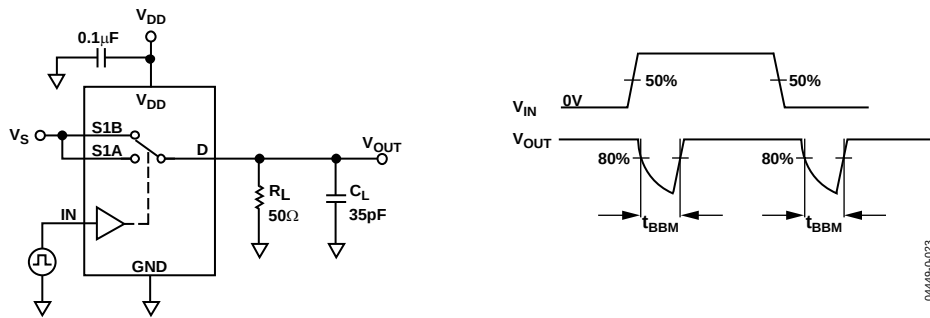


Figure 22. Break-before-Make Time Delay, t_{BBM}

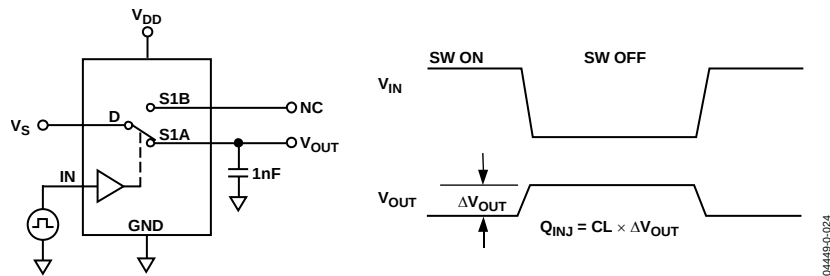
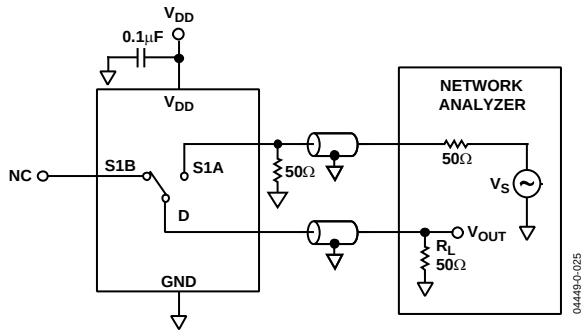
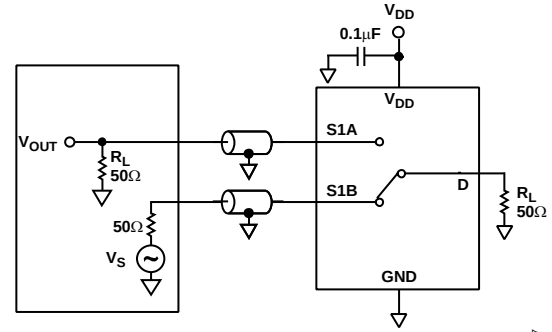


Figure 23. Charge Injection



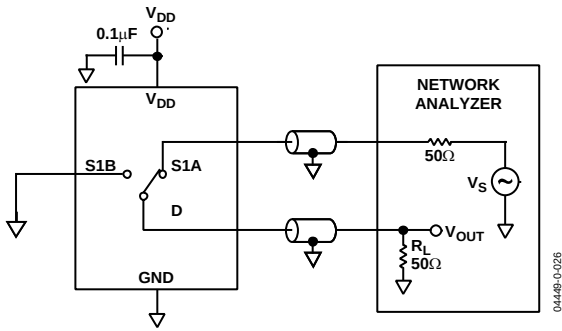
$$\text{OFF ISOLATION} = 20 \text{ LOG } \frac{V_{\text{OUT}}}{V_S}$$

Figure 24. Off Isolation



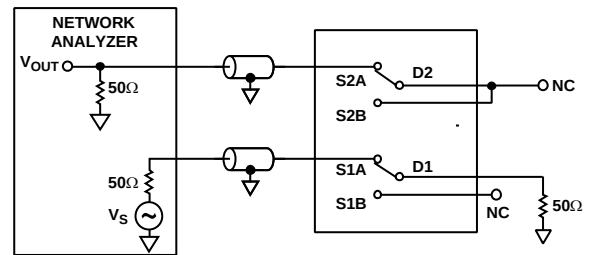
$$\text{CHANNEL-TO-CHANNEL CROSSTALK} = 20 \text{ LOG } \frac{V_{\text{OUT}}}{V_S}$$

Figure 25. Channel-to-Channel Crosstalk (S1A-S1B)



$$\text{INSERTION LOSS} = 20 \text{ LOG } \frac{V_{\text{OUT WITH SWITCH}}}{V_{\text{OUT WITHOUT SWITCH}}}$$

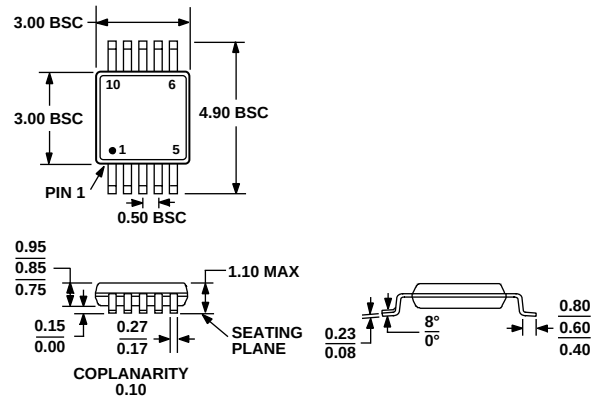
Figure 26. Bandwidth



$$\text{CHANNEL-TO-CHANNEL CROSSTALK} = 20 \text{ LOG } \frac{V_{\text{OUT}}}{V_S}$$

Figure 27. Channel-to-Channel Crosstalk (S1A-S2A)

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-187BA

Figure 28. 10-Lead Mini Small Outline Package [MSOP]
(RM-10)
Dimensions shown in millimeters

ADG836L

ORDERING GUIDE

Model	Temperature Range	Package Description	Package Option	Branding
ADG836LYRM	−40°C to +125°C	Mini Small Outline Package (MSOP)	RM-10	SQA
ADG836LYRM-REEL	−40°C to +125°C	Mini Small Outline Package (MSOP)	RM-10	SQA
ADG836LYRM-REEL7	−40°C to +125°C	Mini Small Outline Package (MSOP)	RM-10	SQA

NOTES

ADG836L

NOTES

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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